

SID

Factory: Rot am See

Article:

560

ML8

Provided:

Landwehr, Melanie

Customer:

Date:

15.12.2015



Processtechnology: B: undefiniert

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1	
A-RS-FR4-Prepreg-7628-TG150-HF	50200643	294		2	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		3	
A-RS-FR4-ML-0.61mm-035+035-TG150-HF	50200659	35	L2	4	A01
		610			
		35	L3		
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	203		5	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		6	
A-RS-FR4-ML-0.61mm-035+035-TG150-HF	50200659	35	L4	7	A02
		610			
		35	L5		
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	203		8	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		9	
A-RS-FR4-ML-0.61mm-035+035-TG150-HF	50200659	35	L6	10	A03
		610			
		35	L7		
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	293		11	
A-RS-FR4-Prepreg-7628-TG150-HF	50200643	0		12	
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	13	

Thickness after Pressing

B00:

3090 µm

Tol+:

320 µm

Tol-:

320 µm

Dmax:

3410 µm

Dmin:

2770 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

3200 µm

Tol+:

320 µm

Tol-:

320 µm

Dmax:

3520 µm

Dmin:

2880 µm

Measuring point: (05) über LM und galv.Cu; beidseitig

nominal:

3069 µm

Version 1.2.14.15

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